

Silicon Carbide Power Schottky Diode

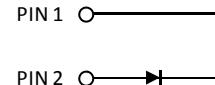
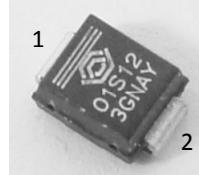
Features

- 1200 V Schottky rectifier
- 175 °C maximum operating temperature
- Temperature independent switching behavior
- Superior surge current capability
- Positive temperature coefficient of V_F
- Extremely fast switching speeds
- Superior figure of merit Q_C/I_F

V_{RRM}	= 1200 V
$I_F (T_c = 25^\circ C)$	= 2.5 A
Q_C	= 7 nC

Package

- RoHS Compliant



SMB / DO – 214AA

Advantages

- Improved circuit efficiency (Lower overall cost)
- Low switching losses
- Ease of paralleling devices without thermal runaway
- Smaller heat sink requirements
- Low reverse recovery current
- Low device capacitance
- Low reverse leakage current at operating temperature

Applications

- Power Factor Correction (PFC)
- Switched-Mode Power Supply (SMPS)
- Solar Inverters
- Wind Turbine Inverters
- Motor Drives
- Induction Heating
- Uninterruptible Power Supply (UPS)
- High Voltage Multipliers

Maximum Ratings at $T_j = 175^\circ C$, unless otherwise specified

Parameter	Symbol	Conditions	Values	Unit
Repetitive peak reverse voltage	V_{RRM}		1200	V
Continuous forward current	I_F	$T_c \leq 160^\circ C$	1	A
RMS forward current	$I_{F(RMS)}$	$T_c \leq 160^\circ C$	2	A
Surge non-repetitive forward current, Half Sine Wave	$I_{F,SM}$	$T_c = 25^\circ C, t_p = 10 \text{ ms}$ $T_c = 160^\circ C, t_p = 10 \text{ ms}$	10 8	A
Non-repetitive peak forward current	$I_{F,max}$	$T_c = 25^\circ C, t_p = 10 \mu\text{s}$	65	A
I^2t value	$\int i^2 dt$	$T_c = 25^\circ C, t_p = 10 \text{ ms}$ $T_c = 160^\circ C, t_p = 10 \text{ ms}$	0.5 0.3	$A^2\text{s}$
Power dissipation	P_{tot}	$T_c = 25^\circ C$	42	W
Operating and storage temperature	T_j, T_{stg}		-55 to 175	$^\circ C$

Electrical Characteristics at $T_j = 175^\circ C$, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Diode forward voltage	V_F	$I_F = 1 \text{ A}, T_j = 25^\circ C$	1.6	1.8	3.7	V
		$I_F = 1 \text{ A}, T_j = 175^\circ C$	2.4			
Reverse current	I_R	$V_R = 1200 \text{ V}, T_j = 25^\circ C$	5	10	100	μA
		$V_R = 1200 \text{ V}, T_j = 175^\circ C$	10			
Total capacitive charge	Q_C	$I_F \leq I_{F,MAX}$	7	13	nC	
		$dI_F/dt = 200 \text{ A}/\mu\text{s}$				
Switching time	t_s	$T_j = 175^\circ C$	$V_R = 400 \text{ V}$ $V_R = 960 \text{ V}$	< 17	ns	
			$V_R = 400 \text{ V}$ $V_R = 960 \text{ V}$			
Total capacitance	C	$V_R = 1 \text{ V}, f = 1 \text{ MHz}, T_j = 25^\circ C$	69		pF	
		$V_R = 400 \text{ V}, f = 1 \text{ MHz}, T_j = 25^\circ C$	10			
		$V_R = 1000 \text{ V}, f = 1 \text{ MHz}, T_j = 25^\circ C$	8			

Thermal Characteristics

Thermal resistance, junction - case	R_{thJC}	3.6	$^\circ C/W$
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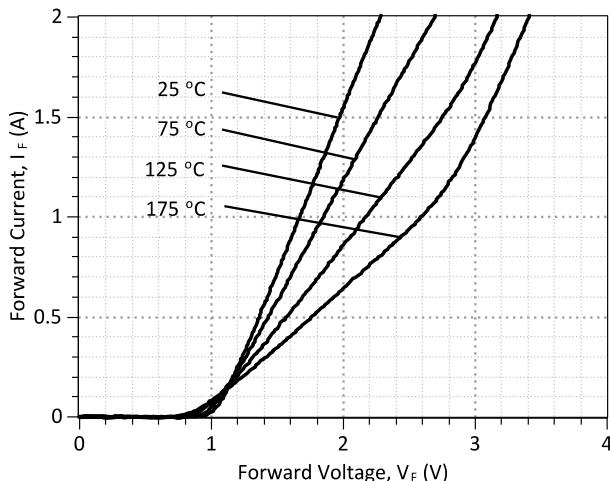


Figure 1: Typical Forward Characteristics

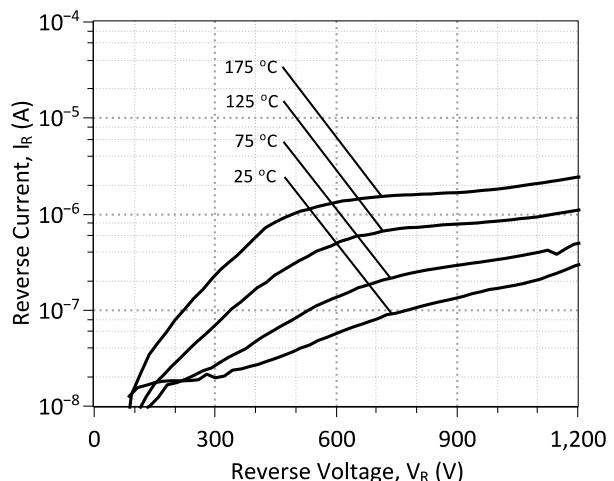


Figure 2: Typical Reverse Characteristics

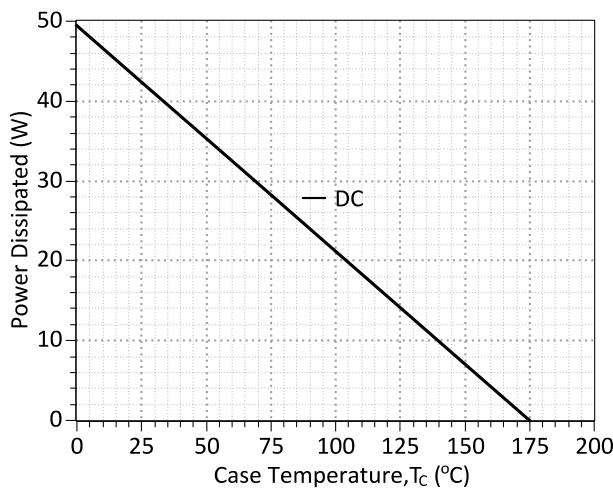


Figure 3: Power Derating Curve

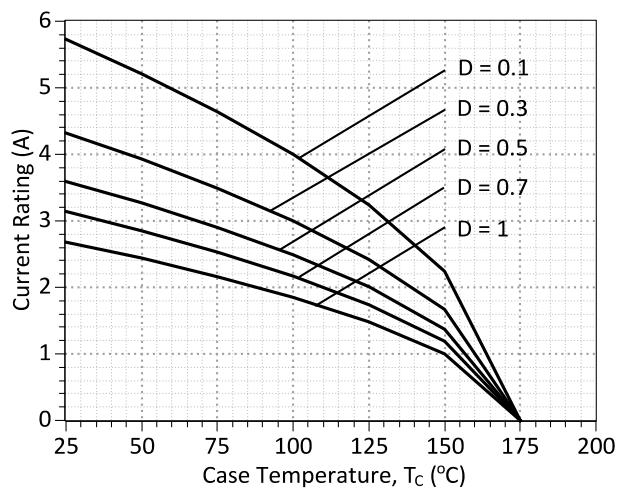


Figure 4: Current Derating Curves ($D = t_p/T$, $t_p = 400 \mu s$)
 (Considering worst case Z_{th} conditions)

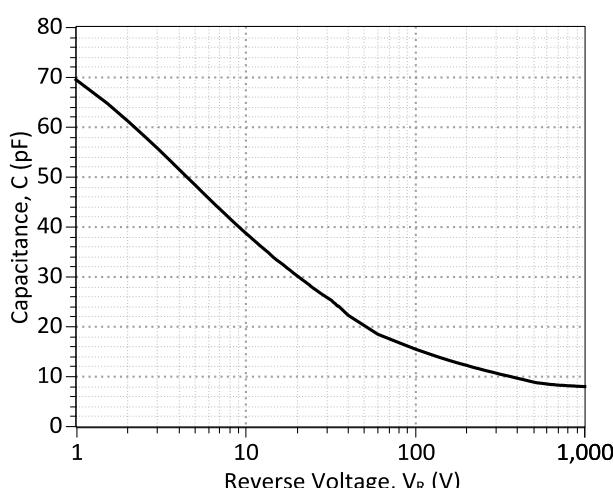


Figure 5: Typical Junction Capacitance vs Reverse Voltage Characteristics

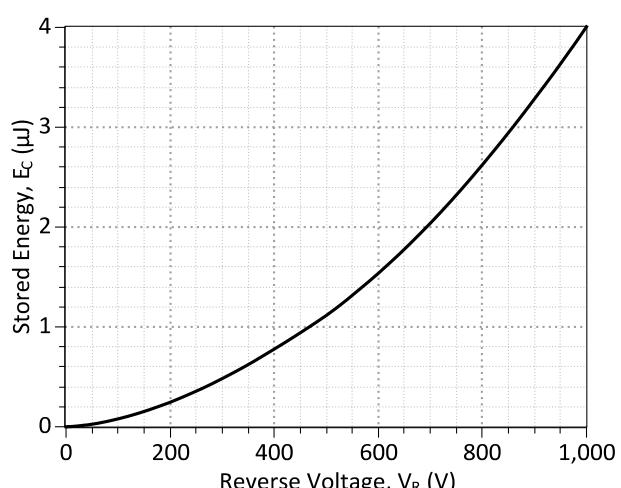


Figure 6: Typical Switching Energy vs Reverse Voltage Characteristics

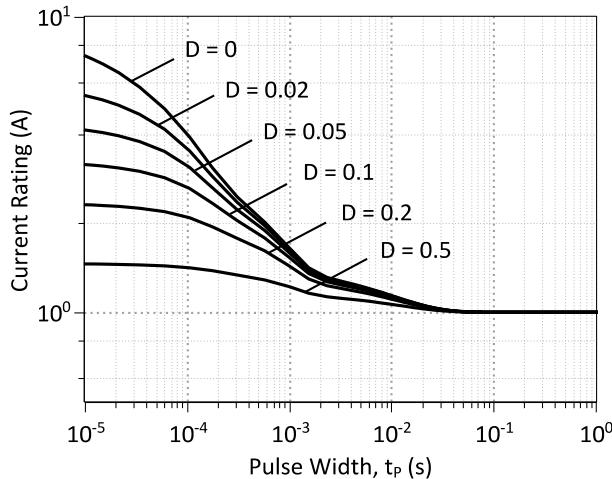


Figure 7: Current vs Pulse Duration Curves at $T_c = 160 \text{ } ^\circ\text{C}$

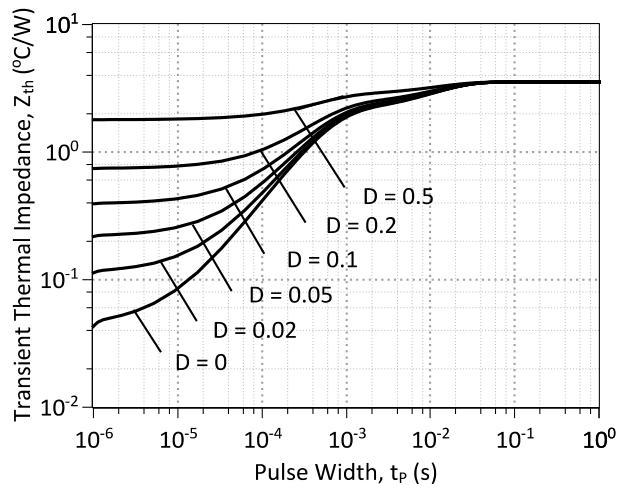
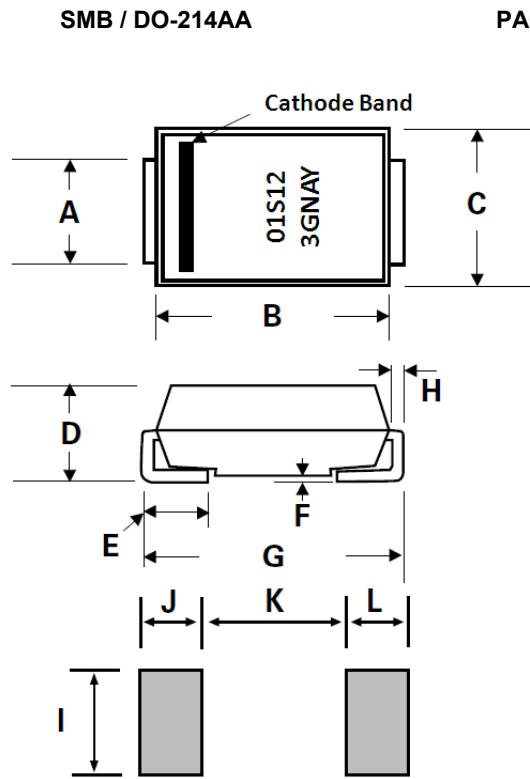


Figure 8: Transient Thermal Impedance

Package Dimensions:



PACKAGE OUTLINE

Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.077	0.086	1.950	2.200
B	0.160	0.180	4.060	4.570
C	0.130	0.155	3.300	3.940
D	0.084	0.096	2.130	2.440
E	0.030	0.060	0.760	1.520
F	-	0.008	-	0.203
G	0.205	0.220	5.210	5.590
H	0.006	0.012	0.152	0.305
I	0.089	-	2.260	-
J	0.085	-	2.160	-
K	-	0.107	-	2.740
L	0.085	-	2.160	-

NOTE

1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS

Revision History			
Date	Revision	Comments	Supersedes
2014/08/26	1	Updated Electrical Characteristics	
2013/09/09	0	Initial release	

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SPICE Model Parameters

Copy the following code into a SPICE software program for simulation of the GB01SLT12-214 device.

```

*      MODEL OF GeneSiC Semiconductor Inc.
*
*      $Revision:    1.0          $
*      $Date:      09-SEP-2013      $
*
*      GeneSiC Semiconductor Inc.
*      43670 Trade Center Place Ste. 155
*      Dulles, VA 20166
*      http://www.genesicsemi.com/index.php/sic-products/schottky
*
*      COPYRIGHT (C) 2013 GeneSiC Semiconductor Inc.
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*
* These models are provided "AS IS, WHERE IS, AND WITH NO WARRANTY
* OF ANY KIND EITHER EXPRESSED OR IMPLIED, INCLUDING BUT NOT LIMITED
* TO ANY IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A
* PARTICULAR PURPOSE."
* Models accurate up to 2 times rated drain current.
*
* Start of GB01SLT12-214 SPICE Model
*
.SUBCKT GB01SLT12 ANODE KATHODE
R1 ANODE INT R=((TEMP-24)*0.0069); Temperature Dependant Resistor
D1 INT KATHODE GB01SLT12_25C; Call the 25C Diode Model
D2 ANODE KATHODE GB01SLT12_PIN; Call the PiN Diode Model
.MODEL GB01SLT12_25C D
+ IS      7.27E-19      RS      0.592251
+ N       1             IKF     407.773
+ EG      1.2            XTI     3
+ CJO     7.90E-11      VJ      0.367
+ M       1.63           FC      0.5
+ TT      1.00E-10      BV      1200
+ IBV     1.00E-03      VPK     1200
+ IAVE    1              TYPE    SiC_Schottky
+ MFG     GeneSiC_Semiconductor
.MODEL GB01SLT12_PIN D
+ IS      1.08E-17      RS      1.8
+ N       2.2313         IKF     999
+ EG      3.23           XTI     -65
+ FC      0.5            TT      0
+ BV      1200            IBV     1.00E-03
+ VPK     1200            IAVE    1
+ TYPE    SiC_PiN
.ENDS
*
* End of GB01SLT12-214 SPICE Model

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